TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOS VI)

2SK3127

Chopper Regulator, DC-DC Converter and Motor Drive Applications

- Low drain-source ON resistance: R_{DS} (ON) = 9.5 Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 38 \text{ S} (typ.)$
- Low leakage current: $I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 30 \ V)$
- Enhancement-mode: $V_{th} = 1.5$ to 3.0 V ($V_{DS} = 10$ V, $I_D = 1$ mA)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	30	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V _{DGR}	30	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	45	٨	
	Pulse (Note 1)	I _{DP}	135	A	
Drain power dissipation $(Tc = 25^{\circ}C)$		PD	65	W	
Single pulse avalanche energy (Note 2)		E _{AS}	524	mJ	
Avalanche current		I _{AR}	45	А	
Repetitive avalanche energy (Note 3)		E _{AR}	6	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	–55 to 150	°C	

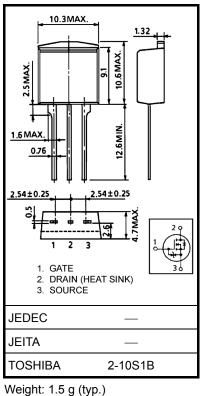
- Note 1: Please use devices on condition that the channel temperature is below 150°C.
- Note 2: V_DD = 25 V, T_{Ch} = 25^{\circ}C (initial), L = 186 $\mu H,~R_G$ = 25 $\Omega,~I_{AR}$ = 45 A
- Note 3: Repetitive rating: pulse width limited by maximum junction temperature.

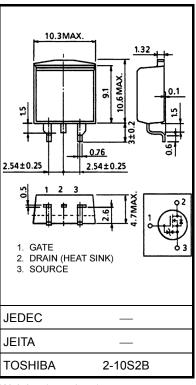
Note 4: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

This transistor is an electrostatic sensitive device. Please handle with caution.

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.92	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W





Weight: 1.5 g (typ.)

Unit: mm

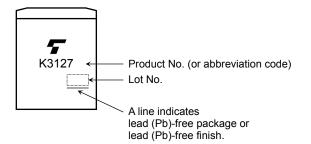
Electrical Characteristics (Ta = 25°C)

Character	istics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS}=\pm 16~V,~V_{DS}=0~V$	_		±10	μA
Drain cut-off current		I _{DSS}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_		100	μA
Drain-source breakdo	wn voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	30			V
Gate threshold voltag	е	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	1.5		3.0	V
Drain-source ON resis	stance	R _{DS (ON)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 25 \text{ A}$		9.5	12	mΩ
Forward transfer adm	ittance	Y _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 25 \text{ A}$	19	40		S
Input capacitance		C _{iss}	V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz	_	2300		pF
Reverse transfer capacitance		C _{rss}	V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz	_	380		pF
Output capacitance		C _{oss}	V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz	_	1100		pF
Switching time	Rise time	tr	V_{GS} V_{GS} V_{GS} V_{OUT} V_{OUT} V_{OUT} V_{GS} V_{OUT} V_{OUT} V_{OUT} V_{OUT} V_{OUT} V_{OUT}	_	12	_	- ns
	Turn-on time	t _{on}		_	25	_	
	Fall time	t _f		_	75	_	
	Turn-off time	t _{off}	V _{DD} ≃ 15 V Duty ≤ 1%, t _w = 10 μs	_	200	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD}\simeq 24$ V, $V_{GS}=10$ V, $I_{D}=45$ A	_	66	_	nC
Gate-source charge		Q _{gs}	$V_{DD}\simeq 24~\text{V},~\text{V}_{GS}=10~\text{V},~\text{I}_{D}=45~\text{A}$		45		nC
Gate-drain ("miller") charge		Q _{gd}	$V_{DD}\simeq 24~\text{V},~\text{V}_{GS}=10~\text{V},~\text{I}_{D}=45~\text{A}$	—	21		nC

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	45	А
Pulse drain reverse current (Note 1)	I _{DRP}		_	_	135	А
Forward voltage (diode)	V _{DSF}	$I_{DR} = 45 \text{ A}, \text{ V}_{GS} = 0 \text{ V}$	—	—	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 45 \text{ A}, V_{GS} = 0 \text{ V},$ $dI_{DR}/dt = 50 \text{ A}/\mu\text{s}$	_	150	_	ns
Reverse recovery charge	Q _{rr}	$I_{DR} = 45 \text{ A}, V_{GS} = 0 \text{ V},$ $dI_{DR}/dt = 50 \text{ A}/\mu\text{s}$	_	270	_	nC

Marking



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20070701-EN

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